

V_{DSS}	600V
$R_{DS(on)}$ (Max.)	0.072Ω
I_D	47A
P_D	120W

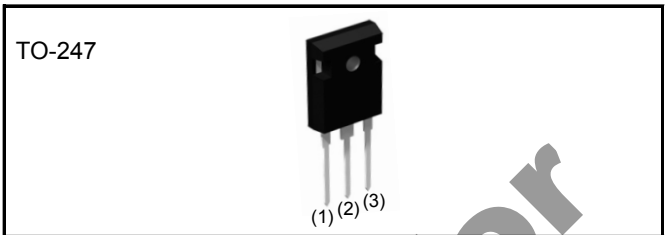
●Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Gate-source voltage (V_{GSS}) guaranteed to be $\pm 20V$.
- 4) Drive circuits can be simple.
- 5) Parallel use is easy.
- 6) Pb-free lead plating ; RoHS compliant

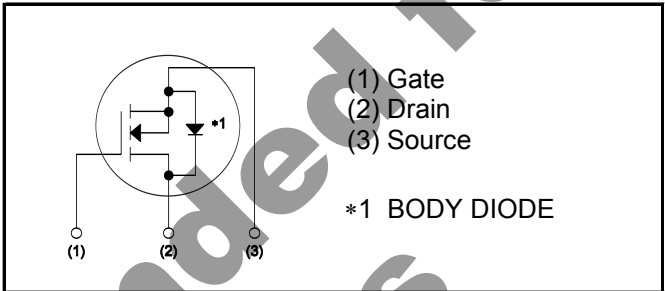
●Application

Switching Power Supply

●Outline



●Inner circuit



●Packaging specifications

Type	Packaging	Tube
	Reel size (mm)	-
	Tape width (mm)	-
	Basic ordering unit (pcs)	450
	Taping code	C9
	Marking	R6047ENZ1

●Absolute maximum ratings ($T_a = 25^\circ C$)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	600	V
Continuous drain current	I_D *1	± 47	A
	I_D *1	± 25.5	A
Pulsed drain current	$I_{D,pulse}$ *2	± 141	A
Gate - Source voltage	V_{GSS}	± 20	V
Avalanche energy, single pulse	E_{AS} *3	1135	mJ
Avalanche energy, repetitive	E_{AR} *3	1.72	mJ
Avalanche current, repetitive	I_{AR}	9.3	A
Power dissipation ($T_c = 25^\circ C$)	P_D	120	W
Junction temperature	T_j	150	$^\circ C$
Range of storage temperature	T_{stg}	-55 to +150	$^\circ C$
Reverse diode dv/dt	dv/dt *4	15	V/ns

●Absolute maximum ratings

Parameter	Symbol	Conditions	Values	Unit
Drain - Source voltage slope	dv/dt	$V_{DS} = 480V$ $T_j = 125^\circ C$	50	V/ns

●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - case	R_{thJC}	-	-	1.04	$^\circ C/W$
Thermal resistance, junction - ambient	R_{thJA}	-	-	30	$^\circ C/W$
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	$^\circ C$

●Electrical characteristics ($T_a = 25^\circ C$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	600	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V$ $T_j = 25^\circ C$	-	0.1	100	μA
		$T_j = 125^\circ C$	-	-	1000	
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_D = 1mA$	2	-	4	V
Static drain - source on - state resistance	$R_{DS(on)}^{*5}$	$V_{GS} = 10V, I_D = 25.8A$ $T_j = 25^\circ C$	-	0.066	0.072	Ω
		$T_j = 125^\circ C$	-	0.140	-	
Gate input resistance	R_G	$f = 1MHz, \text{open drain}$	-	0.8	-	Ω

●Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Transconductance	g_{fs}^{*5}	$V_{DS} = 10\text{V}, I_D = 23.5\text{A}$	13	26	-	S
Input capacitance	C_{iss}	$V_{GS} = 0\text{V}$	-	3850	-	pF
Output capacitance	C_{oss}	$V_{DS} = 25\text{V}$	-	2950	-	
Reverse transfer capacitance	C_{rss}	$f = 1\text{MHz}$	-	320	-	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{GS} = 0\text{V}$ $V_{DS} = 0\text{V to } 480\text{V}$	-	140	-	pF
Effective output capacitance, time related	$C_{o(tr)}$		-	710	-	
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \approx 300\text{V}, V_{GS} = 10\text{V}$ $I_D = 23.5\text{A}$ $R_L = 12.7\Omega$ $R_G = 10\Omega$	-	50	-	ns
Rise time	t_r^{*5}		-	100	-	
Turn - off delay time	$t_{d(off)}^{*5}$		-	260	-	
Fall time	t_f^{*5}		-	100	-	

●Gate Charge characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_g^{*5}	$V_{DD} \approx 300\text{V}$	-	145	-	nC
Gate - Source charge	Q_{gs}^{*5}	$I_D = 47\text{A}$	-	20	-	
Gate - Drain charge	Q_{gd}^{*5}	$V_{GS} = 10\text{V}$	-	80	-	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} \approx 300\text{V}, I_D = 47\text{A}$	-	6.2	-	V

*1 Limited only by maximum temperature allowed.

*2 $P_W \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$

*3 $I_D = 9.3\text{A}, V_{DD} = 50\text{V}$

*4 Reference measurement circuits Fig.5-1.

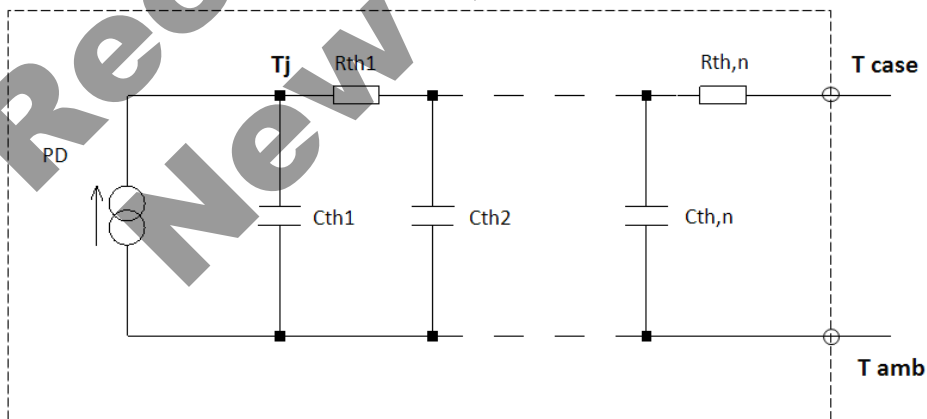
*5 Pulsed

●Body diode electrical characteristics (Source-Drain) ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Inverse diode continuous, forward current	I_S^{*1}	$T_c = 25^\circ\text{C}$	-	-	47	A
Inverse diode direct current, pulsed	I_{SM}^{*2}		-	-	141	A
Forward voltage	V_{SD}^{*5}	$V_{GS} = 0\text{V}, I_S = 47\text{A}$	-	-	1.5	V
Reverse recovery time	t_{rr}^{*5}	$I_S = 47\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$	-	850	-	ns
Reverse recovery charge	Q_{rr}^{*5}		-	18	-	μC
Peak reverse recovery current	I_{rrm}^{*5}		-	45	-	A

●Typical Transient Thermal Characteristics

Symbol	Value	Unit	Symbol	Value	Unit
R_{th1}	0.111	K/W	C_{th1}	0.0246	Ws/K
R_{th2}	0.428		C_{th2}	0.539	
R_{th3}	0.250		C_{th3}	16.7	



●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

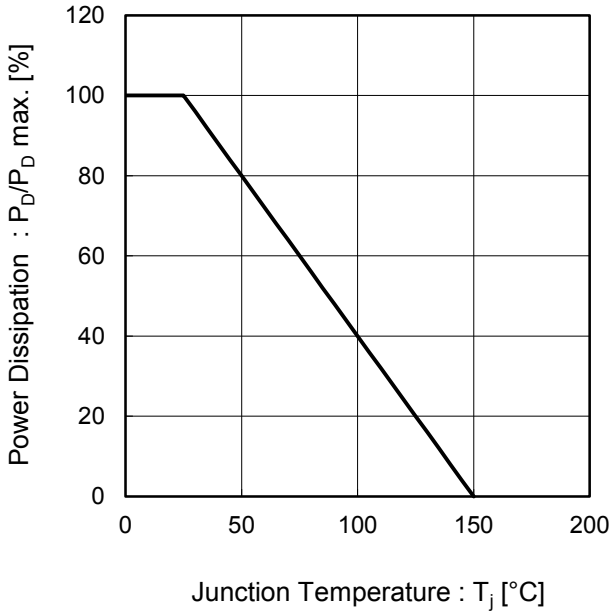


Fig.2 Normalized Transient Thermal Resistance vs. Pulse Width

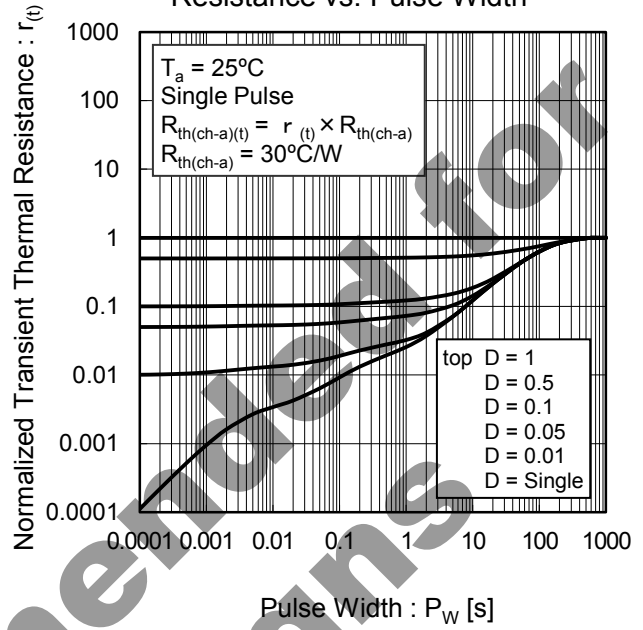
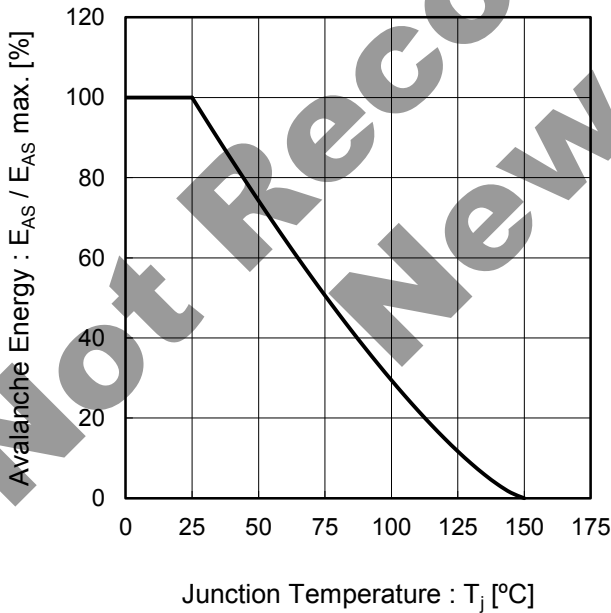


Fig.3 Avalanche Energy Derating Curve vs Junction Temperature



●Electrical characteristic curves

Fig.4 Typical Output Characteristics(I)

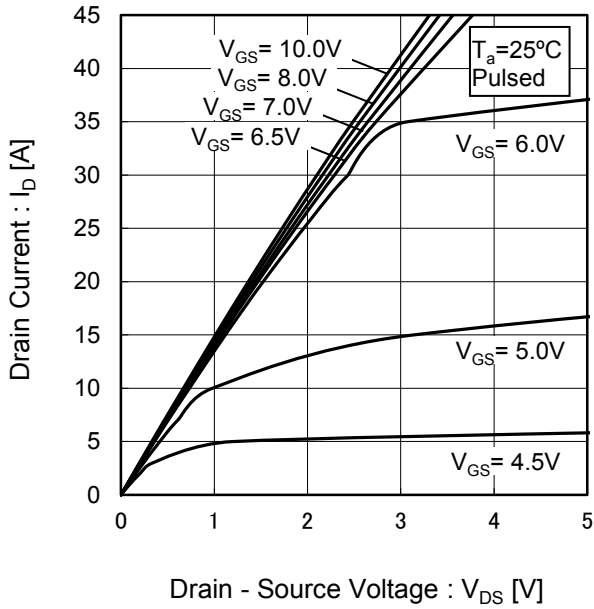


Fig.5 Typical Output Characteristics(II)

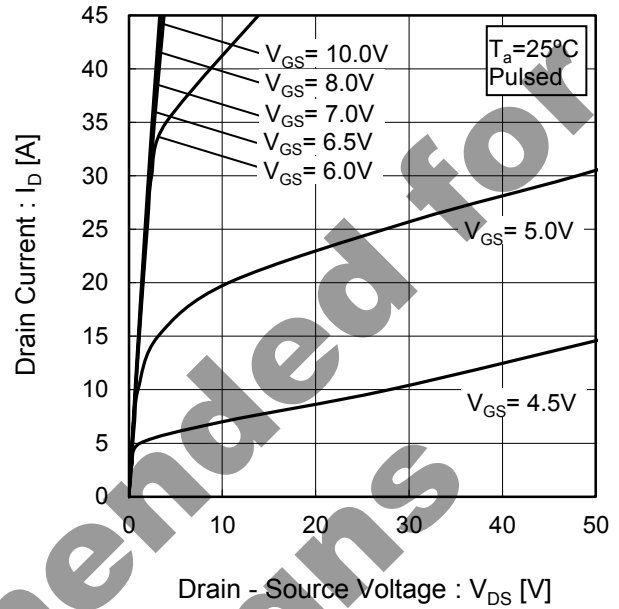


Fig.6 $T_j = 150^\circ\text{C}$ Typical Output Characteristics(I)

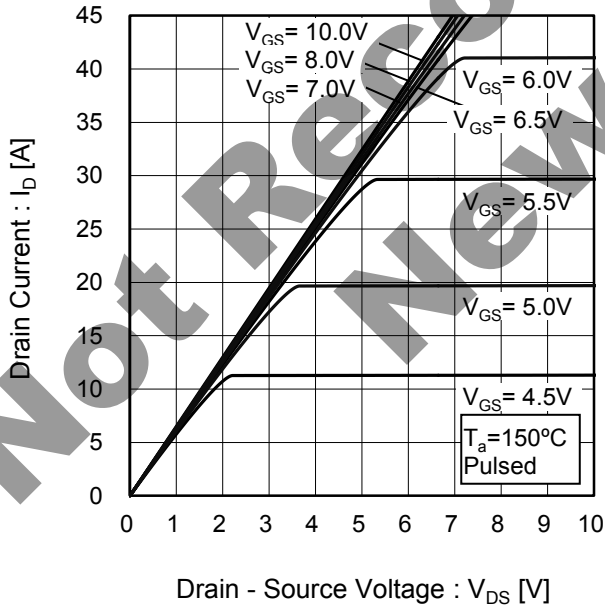
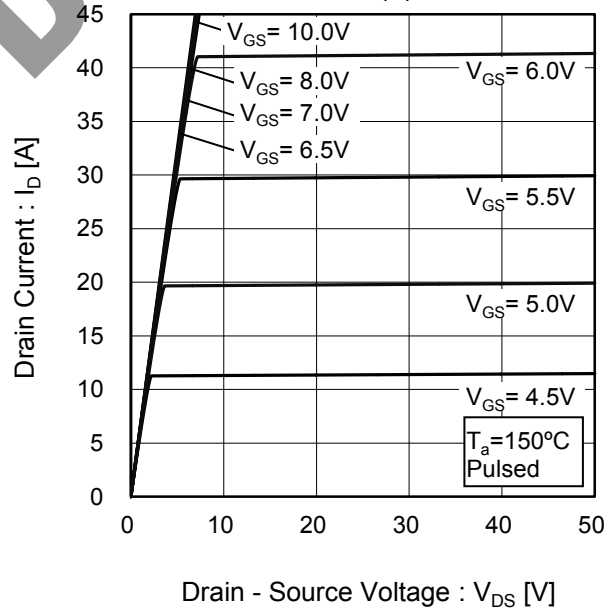


Fig.7 $T_j = 150^\circ\text{C}$ Typical Output Characteristics(II)



●Electrical characteristic curves

Fig.8 Breakdown Voltage vs. Junction Temperature

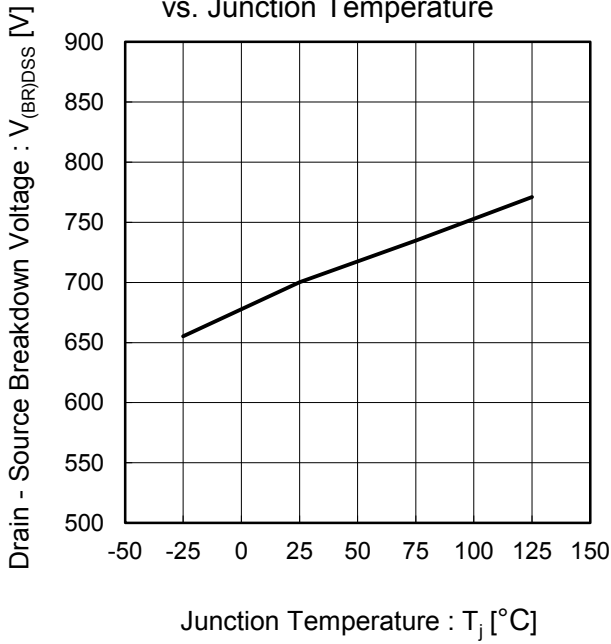


Fig.9 Typical Transfer Characteristics

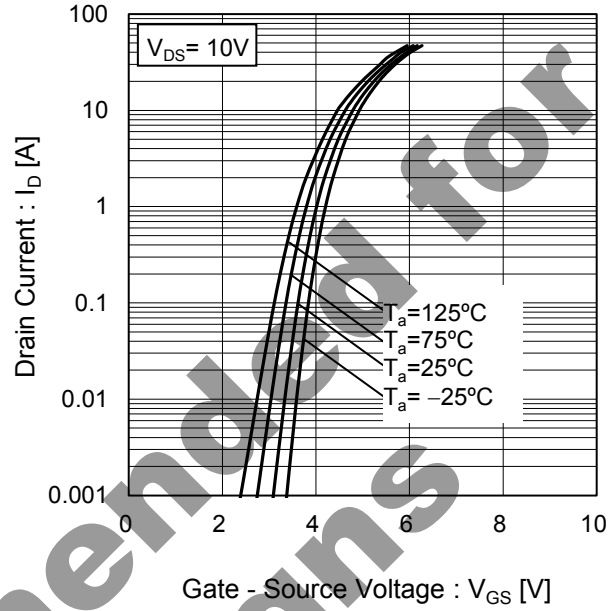


Fig.10 Gate Threshold Voltage vs. Junction Temperature

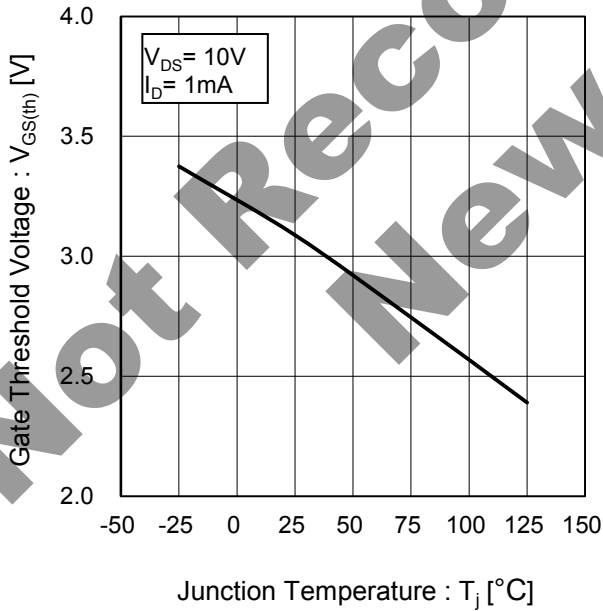
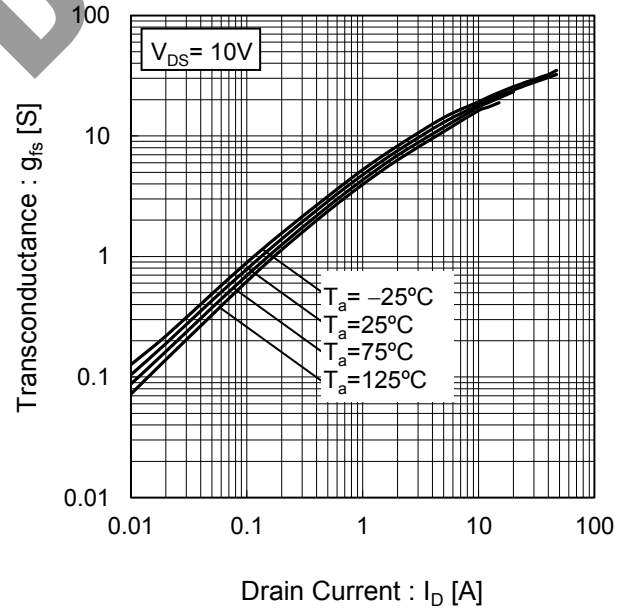


Fig.11 Transconductance vs. Drain Current



●Electrical characteristic curves

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

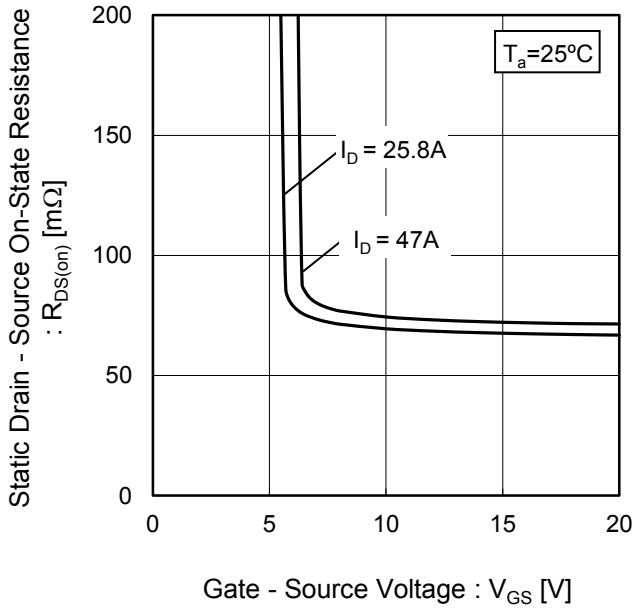


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

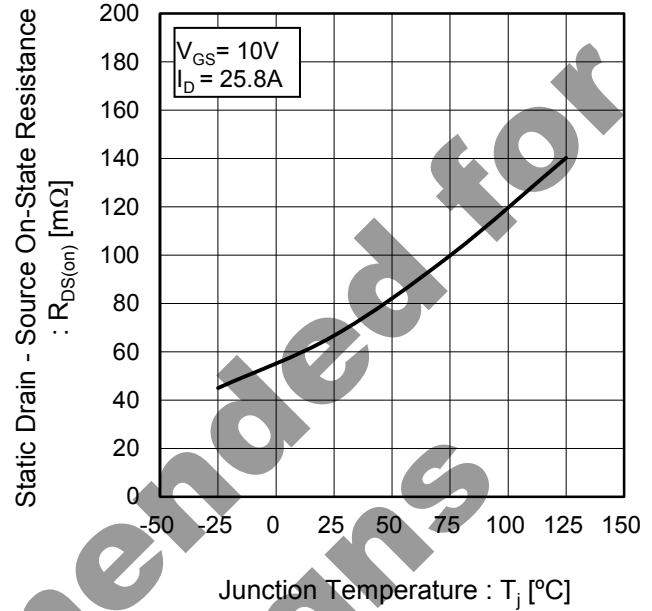


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current

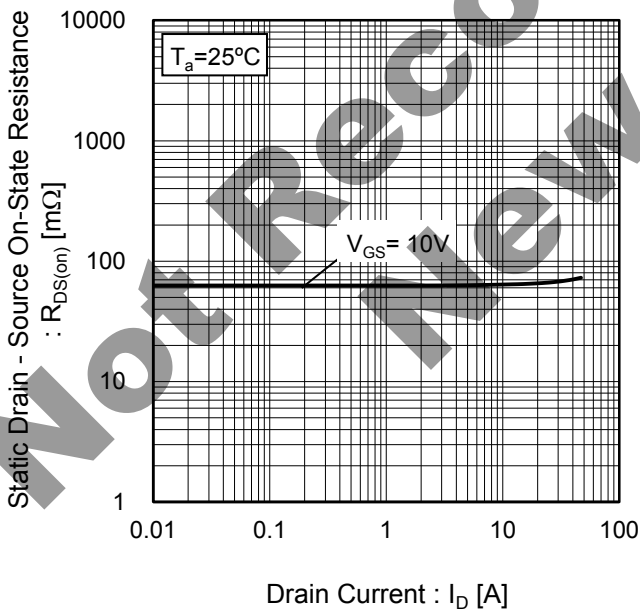
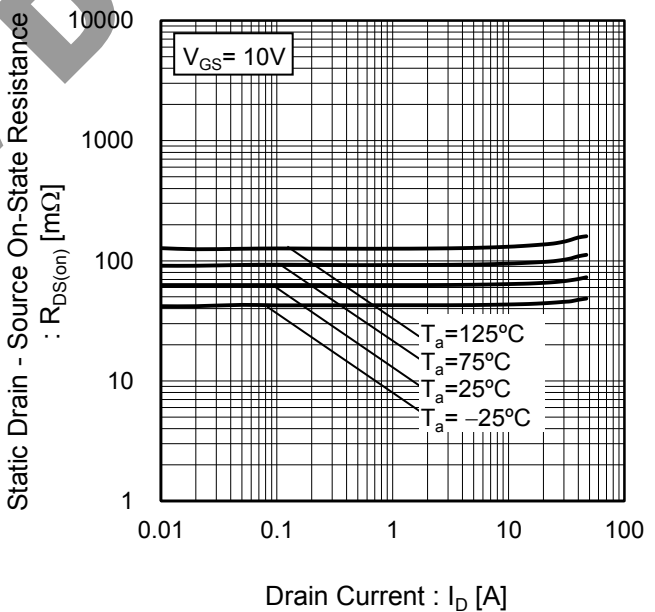


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current



●Electrical characteristic curves

Fig.16 Typical Capacitance vs. Drain - Source Voltage

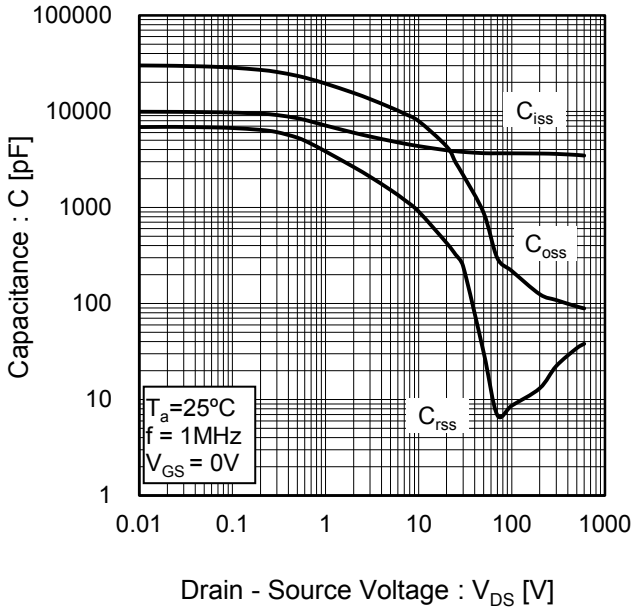


Fig.17 Coss Stored Energy

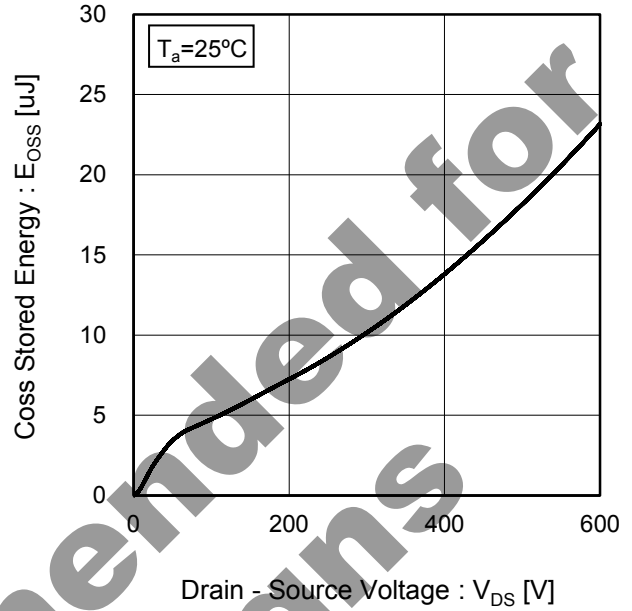


Fig.18 Switching Characteristics

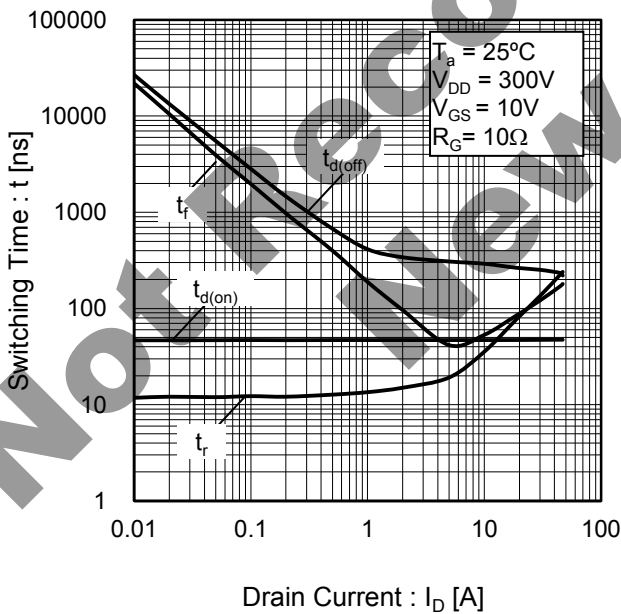
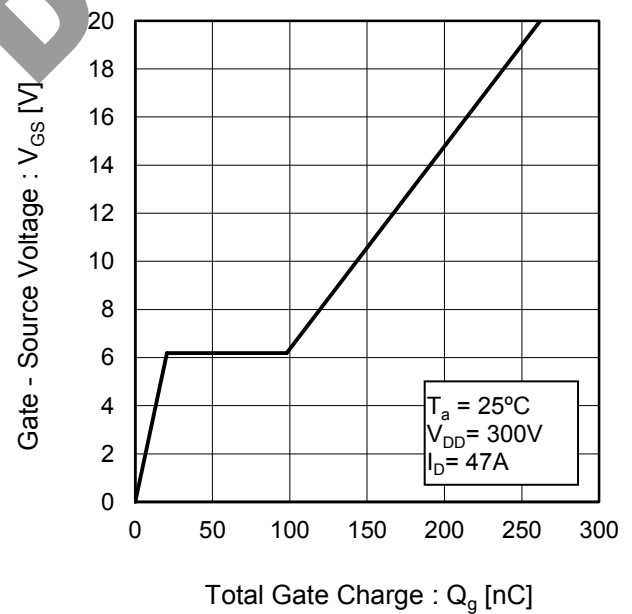


Fig.19 Dynamic Input Characteristics



●Electrical characteristic curves

Fig.20 Inverse Diode Forward Current vs. Source - Drain Voltage

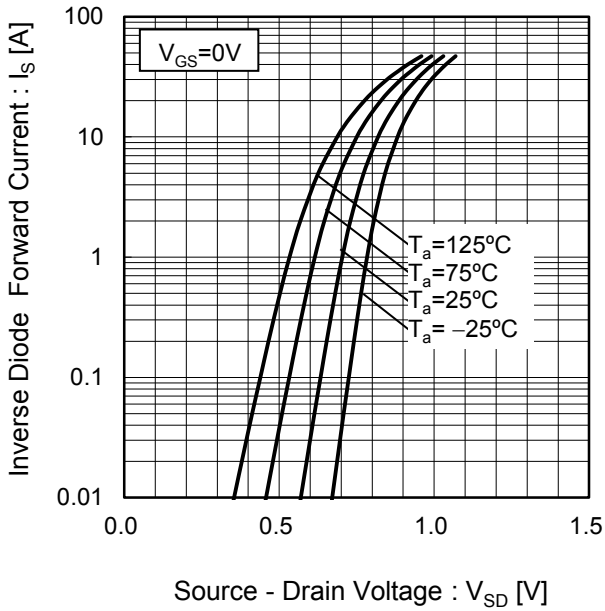
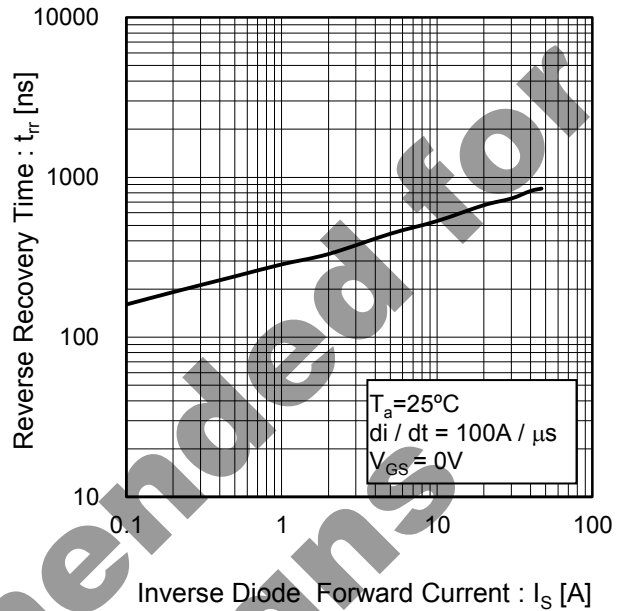


Fig.21 Reverse Recovery Time vs. Inverse Diode Forward Current



Not Recommended for New Designs

● Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

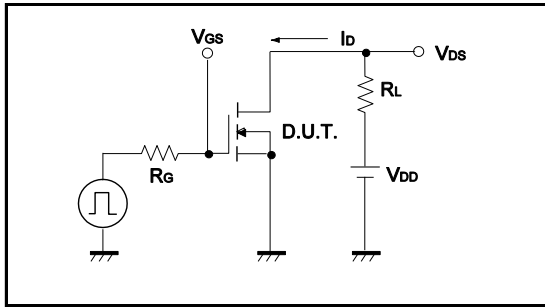


Fig.1-2 Switching Waveforms

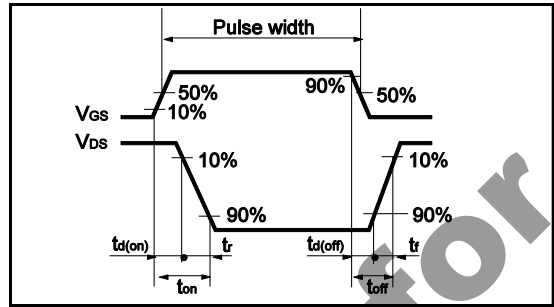


Fig.2-1 Gate Charge Measurement Circuit

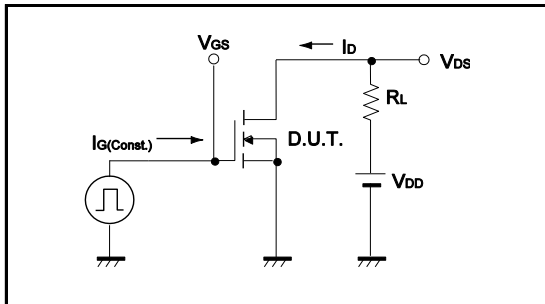


Fig.2-2 Gate Charge Waveform

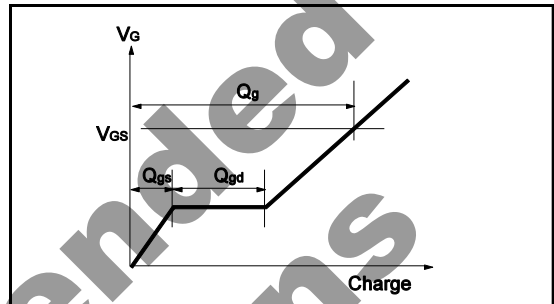


Fig.3-1 Avalanche Measurement Circuit

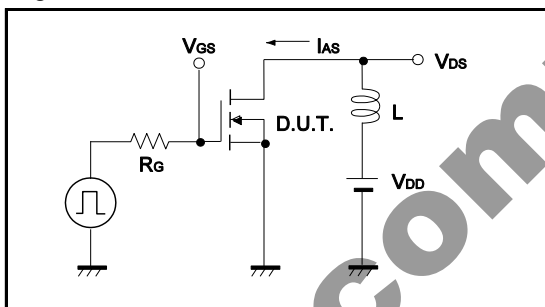


Fig.3-2 Avalanche Waveform

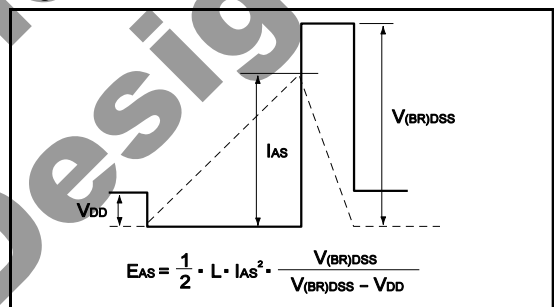


Fig.4-1 dv/dt Measurement Circuit

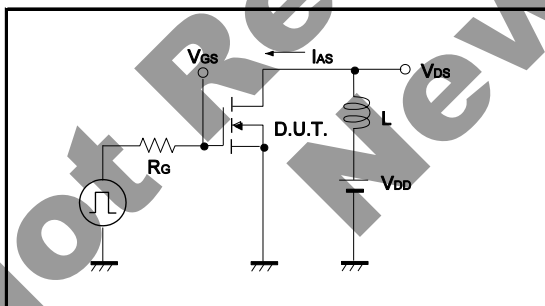


Fig.4-2 dv/dt Waveform

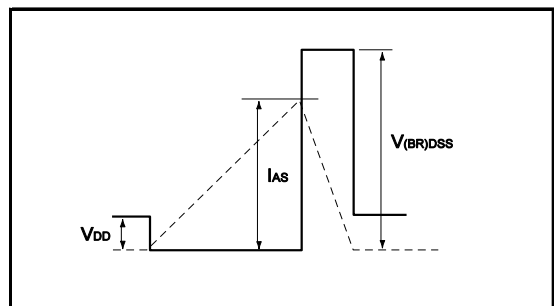


Fig.5-1 di/dt Measurement Circuit

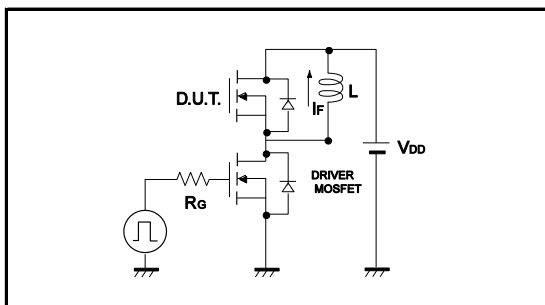
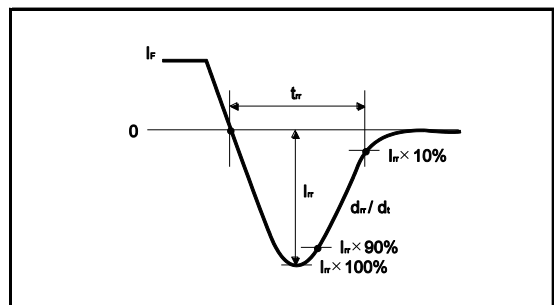
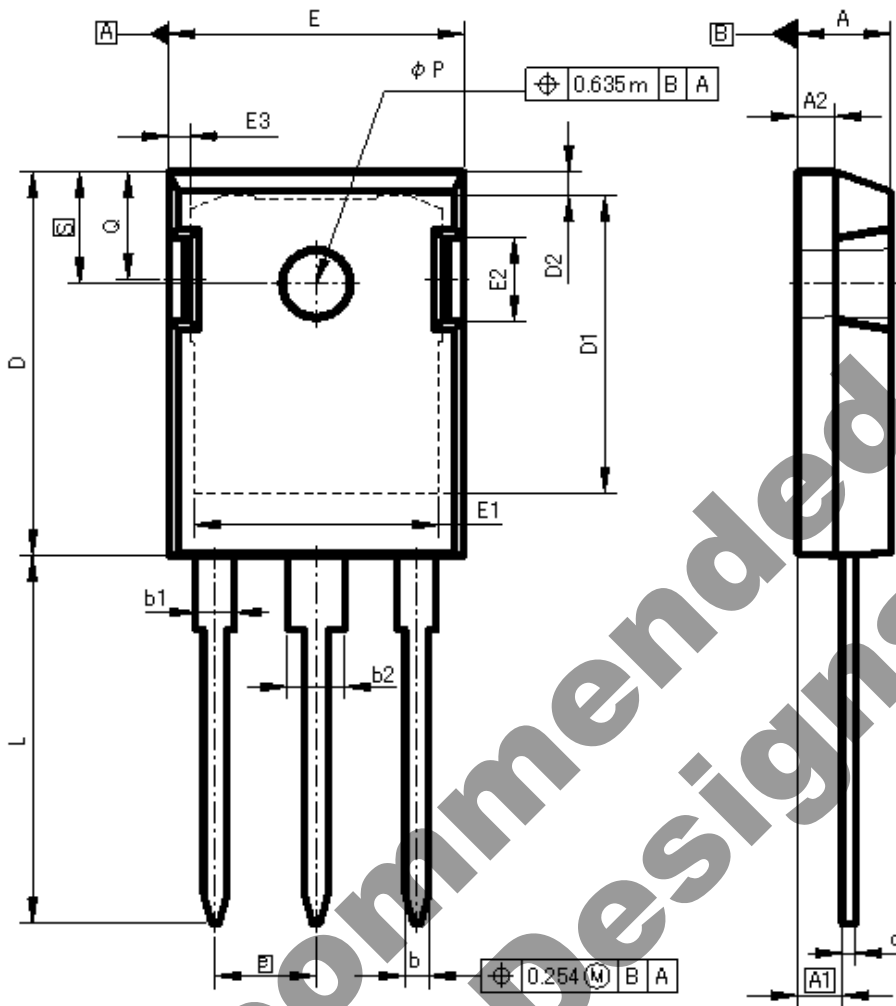


Fig.5-2 di/dt Waveform



●Dimensions (Unit : mm)

TO-247



DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.29	2.54	0.090	0.100
A2	1.91	2.16	0.075	0.085
b	1.14	1.40	0.045	0.055
b1	1.91	2.20	0.075	0.087
b2	2.92	3.20	0.115	0.126
c	0.61	0.80	0.024	0.031
D	20.80	21.34	0.819	0.840
D1	17.43	17.83	0.686	0.702
E	15.75	16.13	0.620	0.635
e	5.45		0.215	
N	3.00		3.000	
L	19.81	20.57	0.780	0.810
L1	3.81	4.32	0.150	0.170
ΦP	3.55	3.65	0.140	0.144
Q	5.59	6.20	0.220	0.244
S	6.15		0.240	

Dimension in mm / inches

Notes

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